Heavy-torque Feel, Low-profile Type SRBD Series

Series Common Info

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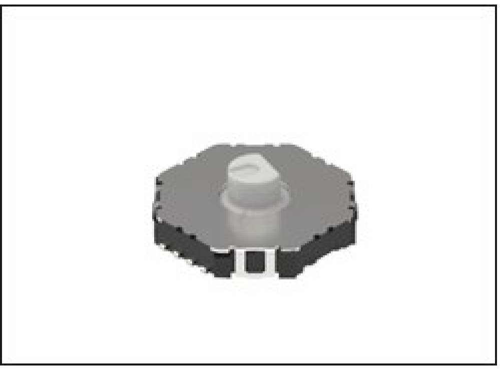
PRINT

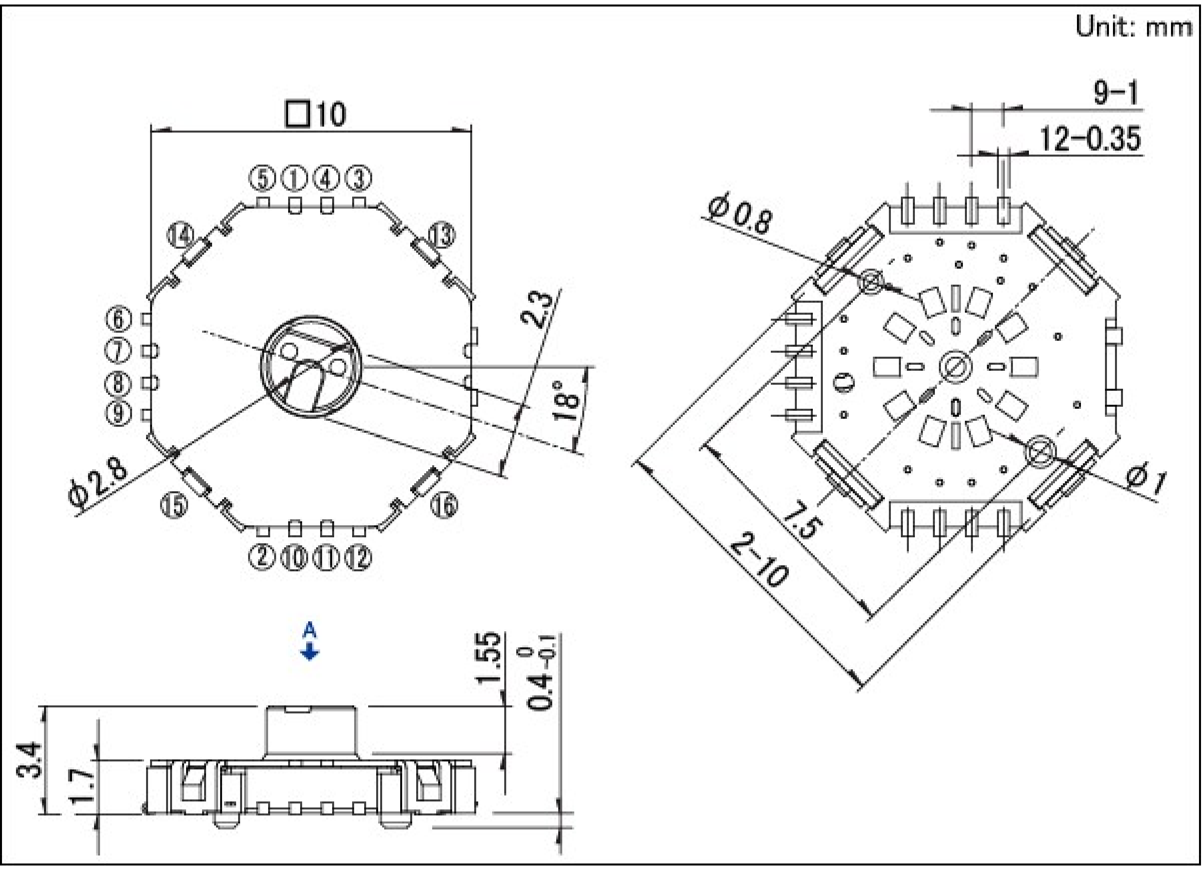
Part number		**SRBD180201**
Poles		1
Positions		10
Changeover angle		36°
Detent		8
Location lug		with
Changeover timing		Non shorting
Rotational torque		13±5mN·m
Soldering		For PC board (Reflow)
Actuator length		1.7mm
Operating temperature range		-25℃ to +85℃
Rating (max.)/(min.) (Resistive load)		1mA 5V DC/50μA 3V DC
Electrical performance	Contact resistance (Initial performance/After lifetime)	200mΩ max./200mΩ max.
	Insulation resistance	100MΩ min. 100V DC
	Voltage proof	100V AC for 1 minute
Mechanical performance	Terminal strength	3N for 1 minute
	Actuator strength Push direction	50N
Durability	Operating life without load	10,000 cycles 250mΩ max.
	Operating life with load (at max. rated load)	10,000 cycles 250mΩ max.
Environmental performance	Cold	-40±2℃ for 500h
	Dry heat	85±2℃ for 500h

	Damp heat	60±2℃, 90 to 95%RH for 500h
Minimum order unit (pcs.)	Japan	1,200
	Export	4,800
3D CAD (STEP)		
Certificate of Compliance to RoHS regulations		

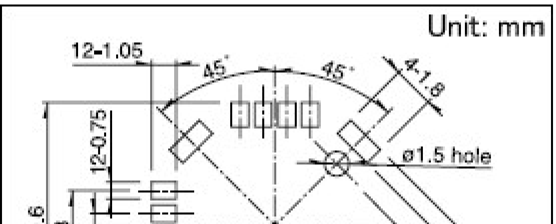
Photo

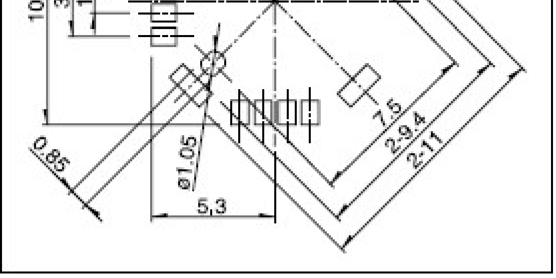


Dimensions



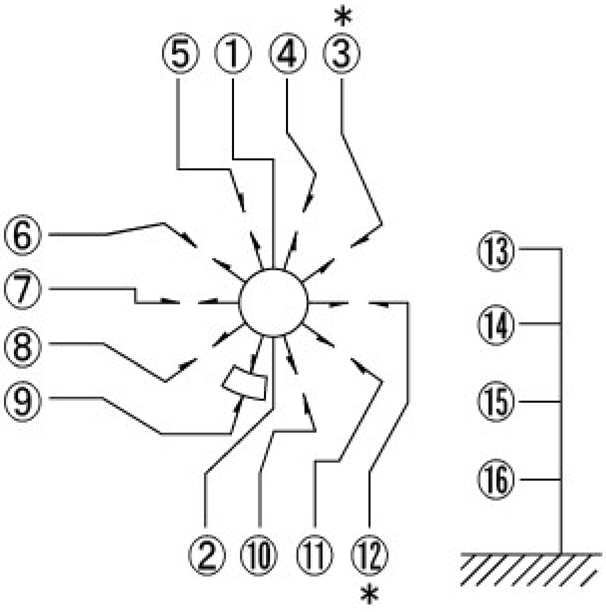
Mounting Hole Dimensions





Viewed from direction A in the dimensions.

Circuit Diagram



*Dummy Terminal

Terminal①② :Common terminal

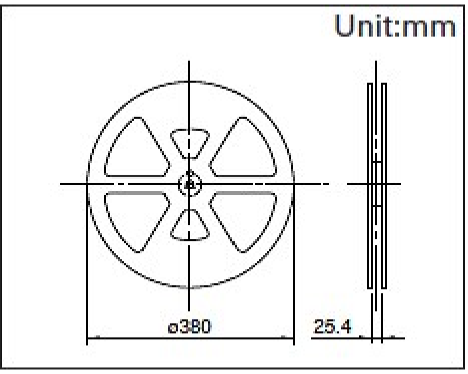
Correspondence Table of Terminal No. and Detent

position No.	Terminal No.	Detent
1	③	—
2	④	○
3	⑤	○
4	⑥	○
5	⑦	○
6	⑧	○
7	⑨	○
8	⑩	○

9	⑪	○
10	⑫	—

Packing Specifications

Taping



Number of packages (pcs.)	1 reel	1,200
	1 case / Japan	2,400
	1 case / export packing	4,800
Tape width (mm)		24
Export package measurements (mm)		428×413×172

Soldering Conditions

Example of Reflow Soldering Condition

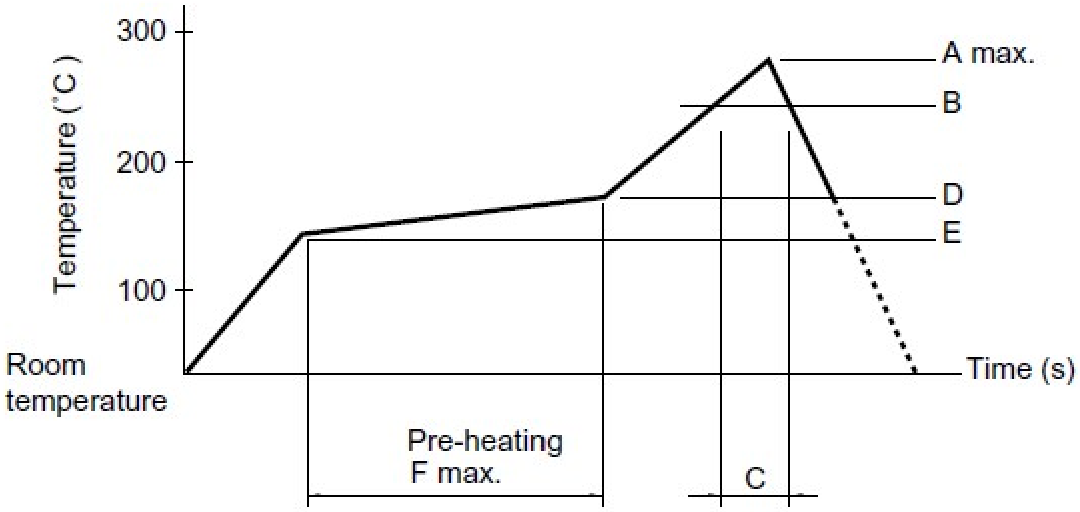
1. Heating method

Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



A(℃)	B(℃)	C(s)	D(℃)	E(℃)	F(s)
3s max.					

260	230	40	180	150	120

(1) The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
(2) Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).

Inquiries about Products

▶ **Inquiry**